

MOS FIELD EFFECT TRANSISTOR 2SK3664

PACKAGE DRAWING (Unit: mm)

0.15^{+0.1}_{-0.05}

0 to 0.1

0.6

 0.75 ± 0.05

1: Source 2: Gate 3: Drain

0.3+0.1

3

0.5

1.0 1.6 ± 0.1

0.1 1.6 ± 0.1

0.8 ±

2

 $0.2^{+0.1}_{-0}$

0.5

N-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

DESCRIPTION

The 2SK3664 is a switching device, which can be driven directly by a 2.5 V power source.

The device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

FEATURES

- 2.5 V drive available
- Low on-state resistance
- $R_{DS(on)1} = 0.57 \Omega MAX. (V_{GS} = 4.5 V, I_{D} = 0.3 A)$ $R_{DS(on)2} = 0.60 \Omega MAX. (V_{GS} = 4.0 V, I_D = 0.3 A)$ $R_{DS(on)3} = 0.88 \Omega MAX. (V_{GS} = 2.5 V, I_{D} = 0.15 A)$

ORDERING INFORMATION

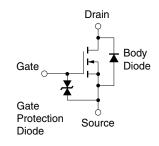
PART NUMBER	PACKAGE
2SK3664	SC-75 (USM)

Marking: G1

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Drain to Source Voltage (Vgs = 0 V)	VDSS	20	V
Gate to Source Voltage (VDs = 0 V)	Vgss	±12	V
Drain Current (DC)	D(DC)	±0.5	А
Drain Current (pulse) Note1	D(pulse)	±2.0	А
Total Power Dissipation Note2	Pτ	0.2	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C

EQUIVALENT CIRCUIT



Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on ceramic substrate of 300 mm² x 0.64 mm

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Caution This product is electrostatic-sensitive device due to low ESD capability and shoud be handled with caution for electrostatic discharge.

VESD = ± 200 V TYP. (C = 200 pF, R = 0 Ω , Single pulse)

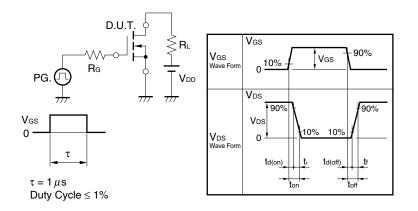
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ELECTRICAL CHARACTERISTICS (TA = 25°C)

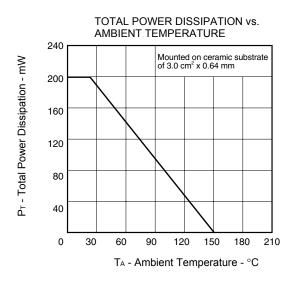
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 20 V, V _{GS} = 0 V			1.0	μA
Gate Leakage Current	lgss	V_{GS} = ±12 V, V_{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1.0 mA	0.5	1.0	1.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 0.3 A	0.25	0.75		S
Drain to Source On-state Resistance ^{Note}	RDS(on)1	Vgs = 4.5 V, Id = 0.3 A		0.38	0.57	Ω
	RDS(on)2	Vgs = 4.0 V, Id = 0.3 A		0.41	0.60	Ω
	RDS(on)3	Vgs = 2.5 V, Id = 0.15 A		0.60	0.88	Ω
Input Capacitance	Ciss	V _{DS} = 10 V		28		pF
Output Capacitance	Coss	V _{GS} = 0 V		11		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		7.0		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10 V, I _D = 0.30 A		20		ns
Rise Time	tr	V _{GS} = 4.0 V		51		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		94		ns
Fall Time	tr]		87		ns
Body Diode Forward Voltage Note	V _{F(S-D)}	IF = 0.5 A, VGS = 0 V		0.87		V

Note Pulsed

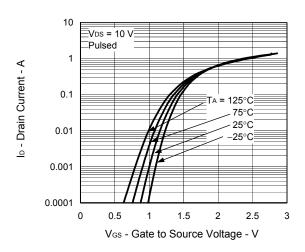
TEST CIRCUIT SWITCHING TIME

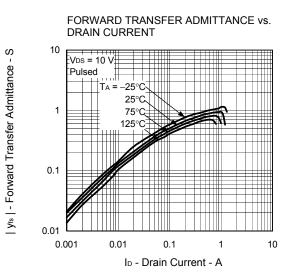


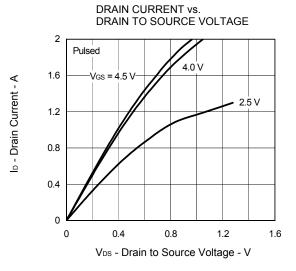




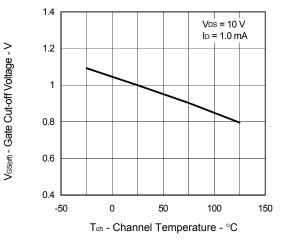
FORWARD TRANSFER CHARACTERISTICS



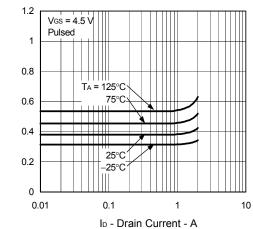




GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

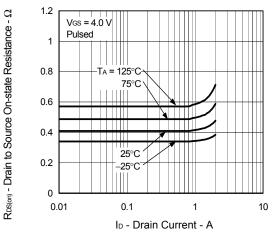


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

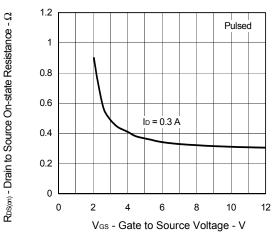


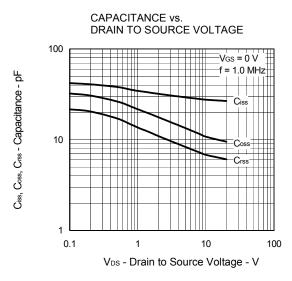
 $R_{\text{DS}(\text{on})}$ - Drain to Source On-state Resistance - Ω

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

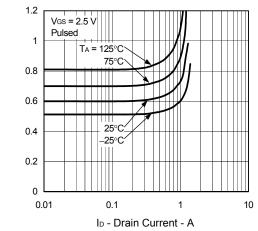


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE





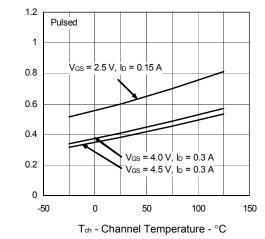
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



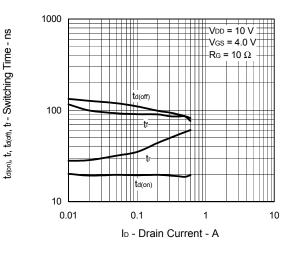
 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - Ω

 $R_{DS(m)}$ - Drain to Source On-state Resistance - Ω

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

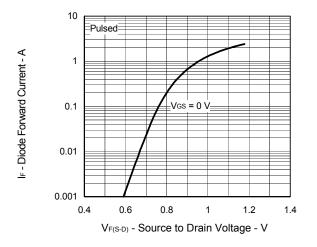


SWITCHING CHARACTERISTICS



NEC

SOURCE TO DRAIN DIODE FORWARD VOLTAGE



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